

# Infrared Transceiver Module (SIR, 115.2 kbit/s) for IrDA® Applications



#### **DESCRIPTION**

TFBS9711 is an infrared transceiver that supports data rates up to 115 kbit/s per the IrDA standard. The link distance is up to 1 meter. The transceiver includes a PIN photodiode, an infrared emitter, and a low-power control IC. These components have not been qualified according to automotive specifications.

#### **FEATURES**

- Compliant to the IrDA physical layer specification
- Standard IrDA link distance of 1 m
- Low power consumption, typically less than 70 μA
- Less than 1 μA in shutdown mode
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE GREEN (5-2008)

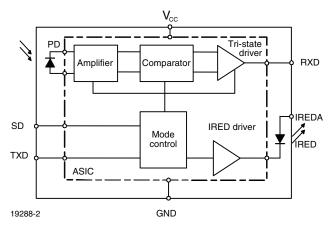
#### **APPLICATIONS**

- · Short-distance wireless communication and data transfer
- Use in environments where RF is problematic

#### **DESIGN SUPPORT TOOLS**

- 3D model
- Window size calculator
- Symbols and terminology
- IRDC protocol
- Reference layouts and circuit diagrams

#### **FUNCTIONAL BLOCK DIAGRAM**



#### **LINKS TO ADDITIONAL RESOURCES**







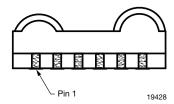
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PRODUCT SUMMARY									
PART NUMBER	DATA RATE (kbit/s)	DATA RATE HYLYW LINK DISTANCE VOLTAGE			IDLE SUPPLY CURRENT (mA)				
TFBS9711	115.2	1.9 x 6 x 3	0 to ≥ 1	2.4 to 5.5	0.07				

PARTS TABLE				
PART NUMBER DESCRIPTION QTY/REE				
TFBS9711-TR1	Oriented in carrier tape for side view surface mounting	1000 pcs		
TFBS9711-TR3	Oriented in carrier tape for side view surface mounting	2500 pcs		
TFBS9711-TT1	Oriented in carrier tape for top view surface mounting	1000 pcs		

#### **PINOUT**

TFBS9711 weight 43 mg



#### **Definitions:**

In the Vishay transceiver datasheets the following nomenclature is used for defining the IrDA operating modes: SIR: 2.4 kbit/s to 115.2 kbit/s, equivalent to the basic serial infrared standard with the physical layer version IrPhy 1.0.

PIN DE	PIN DESCRIPTION								
PIN NUMBER	SYMBOL	DESCRIPTION	I/O	ACTIVE					
1	V <sub>CC2</sub> IRED anode	Connect IRED anode directly to the power supply (V <sub>CC2</sub> ). IRED current can be decreased by adding a resistor in series between the power supply and IRED anode. A separate unregulated power supply can be used at this pin							
2	TXD	This Schmitt-Trigger input is used to transmit serial data when SD is low. An on-chip protection circuit disables the LED driver if the TXD pin is asserted for longer than 100 µs. The input threshold voltage adapts to and follows the logic voltage swing defined by the applied supply voltage	I	High					
3	RXD	Received data output, push-pull CMOS driver output capable of driving standard CMOS or TTL loads. During transmission the RXD output is active and mirrors the transmit signal. No external pull-up or pull-down resistor is required. Floating with a weak pull-up of 500 k $\Omega$ (typ.) in shutdown mode. The voltage swing is defined by the applied supply voltage	0	Low					
4	SD	Shutdown. The input threshold voltage adapts to and follows the logic voltage swing defined by the applied supply voltage	1	High					
5	V <sub>CC1</sub>	Supply voltage							
6	GND	Ground							



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ABSOLUTE MAXIMUM RATINGS									
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNIT			
Supply voltage range, transceiver	-0.3 V < V <sub>CC2</sub> < 6 V	V <sub>CC1</sub>	-0.5	-	+6	V			
Supply voltage range, transmitter	-0.5 V < V <sub>CC1</sub> < 6 V	V <sub>CC2</sub>	-0.5	-	+6	V			
RXD output voltage	-0.5 V < V <sub>CC1</sub> < 6 V	$V_{RXD}$	-0.5	-	$V_{CC1} + 0.5$	V			
Voltage at all inputs	Note: V <sub>in</sub> ≥ V <sub>CC1</sub> is allowed	V <sub>in</sub>	-0.5	-	+6	V			
Input current	For all pins except IRED anode pin	I <sub>CC</sub>	-	-	10	mA			
Output sink current			-	-	25	mA			
Power dissipation		$P_{D}$	-	-	250	mW			
Junction temperature		Tj	-	-	125	°C			
Ambient temperature range (operating)		T <sub>amb</sub>	-25	-	+85	°C			
Storage temperature range		T <sub>stg</sub>	-25	-	+85	°C			
Soldering temperature	See recommended solder profile		-	-	260	°C			
Average output current, pin 1		I <sub>IRED</sub> (DC)	-	-	85	mA			
Repetitive pulsed output current pin 1 to pin 2	JESD22-A114	I <sub>IRED</sub> (RP)	-	-	430	mA			
ESD protection	JESD78	V <sub>ESD</sub>	2	-	-	kV			
Latchup			± 100	-	-	mA			
Thermal resistance junction to ambient	JESD51	R <sub>thJA</sub>	-	300	-	K/W			

#### Note

•	Reference	point	ground,	pin	6	unless	otherwise	noted.
	Typical values are for	design aid only, r	not guaranteed nor si	ubject to produc	ction testing			

EYE SAFETY INFORMATION	
STANDARD	CLASSIFICATION
IEC/EN 60825-1 (2007-03), DIN EN 60825-1 (2008-05) "SAFETY OF LASER PRODUCTS - Part 1: equipment classification and requirements", simplified method	Class 1
IEC 62471 (2006), CIE S009 (2002) "Photobiological Safety of Lamps and Lamp Systems"	Exempt
DIRECTIVE 2006/25/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL of 5 <sup>th</sup> April 2006 on the minimum health and safety requirements regarding the exposure of workers to risks arising from physical agents (artificial optical radiation) (19 <sup>th</sup> individual directive within the meaning of article 16(1) of directive 89/391/EEC)	Exempt

#### Note

• Vishay transceivers operating inside the absolute maximum ratings are classified as eye safe according the above table



<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>amb</sub> = 25 °C, V <sub>CC1</sub> = V <sub>CC2</sub> = 2.4 V to 5.5 V unless otherwise noted)								
PARAMETER	TEST CONDITIONS SYMBOL MIN.		MIN.	TYP.	MAX.	UNIT		
TRANSCEIVER								
Supply voltage		V <sub>CC1</sub>	2.4	-	5.5	V		
Data rates			9.6	-	115.2	kbit/s		
Idle supply current at V <sub>CC1</sub> (receive mode, no signal)	$SD = low, \\ T_{amb} = -25  ^{\circ}\text{C to } +85  ^{\circ}\text{C} \\ \text{independent of ambient light,} \\ V_{CC1} = V_{CC2} = 2.4  \text{V to } 5.5  \text{V} \\ \end{cases}$	I <sub>CC1</sub>	40	70	150	μА		
Average dynamic supply current, transmitting	I <sub>IRED</sub> = 300 mA, 20 % duty cycle	I <sub>CC1</sub>	-	0.6	2	mA		
Standby (SD) (1) supply current	SD = high, T <sub>amb</sub> = -25 °C to +85 °C, independent of ambient light	I <sub>SD</sub>	-	0.01	1	μΑ		
RXD to V <sub>CC1</sub> impedance	SD = high	R <sub>RXD</sub>	400	500	600	kΩ		
Input voltage low (TXD, SD)		$V_{ILo}$	-0.3	-	0.4	V		
Input voltage high (SD)	For compliance with I <sub>SD</sub> spec.	V <sub>IHi</sub>	V <sub>CC1</sub> - 0.3	-	6	V		
Input voltage high (TXD)		V <sub>IHi</sub>	V <sub>CC1</sub> - 0.5	-	6	V		
Input leakage current low	$V_{ILo} \le 0.3 \text{ V}$	I <sub>ILO</sub>	-	0.01	10	μΑ		
Input leakage current high	$V_{IHi} \ge V_{CC1} - 0.3 V$	I <sub>IHi</sub>	-	0.01	10	μΑ		
Input capacitance (TXD, SD)		C <sub>IN</sub>	-	-	5	pF		
Output voltage low, RXD	$C_{load} = 8 \text{ pF}, I_{OLo} \le  +500  \mu\text{A} $	V <sub>OLo</sub>	-	-	0.15 x V <sub>CC1</sub>	V		
Output voltage high, RXD	I <sub>OH</sub> = -200 μA	V <sub>OHi</sub>	0.8 x V <sub>CC1</sub>	-	-	V		

#### Notes

- Typical values are for design aid only, not guaranteed nor subject to production testing
- (1) SD mode becomes active when SD is set high for more than 0.2 µs. In SD mode the detector is disabled and the output disconnected

<b>OPTOELECTRONIC CHARACTERISTICS</b> ( $T_{amb} = 25  ^{\circ}C$ , $V_{CC1} = V_{CC2} = 2.4  \text{V}$ to $5.5  \text{V}$ unless otherwise noted)								
PARAMETER	ARAMETER TEST CONDITIONS SYMBOL MIN. TYP.							
RECEIVER								
Minimum irradiance E <sub>e</sub> in angular range <sup>(1)</sup>	9.6 kbit/s to 115.2 kbit/s $\lambda = 850 \text{ nm to } 900 \text{ nm, } \alpha = 0^{\circ}, 15^{\circ}$	E <sub>e</sub>	-	35	80	mW/m <sup>2</sup>		
Maximum irradiance E <sub>e</sub> in angular range <sup>(2)</sup>	λ = 850 nm to 900 nm	E <sub>e</sub>	2	5	-	kW/m²		
Maximum no detection irradiance (3)	$\begin{split} \lambda = 850 \text{ nm to } 900 \text{ nm, } t_r, t_f < 40 \text{ ns,} \\ t_{po} = 1.6  \mu\text{s at } f = 115 \text{ kHz,} \\ \text{no output signal allowed} \end{split}$	E <sub>e</sub>	4	-	-	mW/m²		
Rise time of output signal	10 % to 90 %, C <sub>L</sub> = 8 pF	t <sub>r(RXD)</sub>	10	30	80	ns		
Fall time of output signal	90 % to 10 %, C <sub>L</sub> = 8 pF	t <sub>f(RXD)</sub>	10	30	80	ns		
RXD pulse width of output signal <sup>(4)</sup>	Input pulse length > 1.2 μs	t <sub>PW</sub>	1.7	2.2	3	μs		
Stochastic jitter, leading edge Input irradiance = 100 mW/m², ≤ 115.2 kbit/s			-	-	350	ns		
Standby/shutdown delay, receiver startup time			-	100	500	μs		
Latency		t <sub>L</sub>	-	50	150	μs		



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<b>OPTOELECTRONIC CHARACTERISTICS</b> ( $T_{amb} = 25  ^{\circ}C$ , $V_{CC1} = V_{CC2} = 2.4  \text{V}$ to $5.5  \text{V}$ unless otherwise noted)									
PARAMETER	TEST CONDITIONS	TYP.	MAX.	UNIT					
TRANSMITTER									
IRED operating current limitation	No external resistor for current limitation <sup>(5)</sup>	$I_{D}$	200	300	430	mA			
Forward voltage of built-in IRED	I <sub>F</sub> = 300 mA	$V_{f}$	1.4	1.8	1.9	V			
Output leakage IRED current	$TXD = 0 V, 0 < V_{CC1} < 5.5 V$	I <sub>IRED</sub>	-1	0.01	1	μΑ			
	$\alpha$ = 0°, 15° TXD = high, SD = low, R <sub>1</sub> = 0 $\Omega$	l <sub>e</sub>	40	140	300	mW/sr			
Output radiant intensity (5)	$V_{CC1} = 5 \text{ V}, \alpha = 0^{\circ}, 15^{\circ},$ TXD = low or SD = high (receiver is inactive as long as SD = high)	l <sub>e</sub>	-	-	0.04	mW/sr			
Output radiant intensity, angle of half intensity		α	-	± 24	-	deg			
Peak-emission wavelength		$\lambda_{p}$	870	-	910	nm			
Spectral bandwidth		Δλ	-	45	-	nm			
Optical rise time		t <sub>ropt</sub>	10	50	300	ns			
Optical fall time		t <sub>fopt</sub>	10	50	300	ns			
Optical output pulse duration	Input pulse width 1.6 < t <sub>TXD</sub> < 23 µs	t <sub>opt</sub>	t <sub>TXD</sub> - 0.15	-	t <sub>TXD</sub> + 0.15	μs			
Optical output pulse duration	Input pulse width t <sub>TXD</sub> ≥ 23 µs	t <sub>opt</sub>	23	50	100	μs			
Optical overshoot		-	-	-	25	%			

#### Notes

- · Typical values are for design aid only, not guaranteed nor subject to production testing
- (1) IrDA sensitivity definition: minimum irradiance E<sub>e</sub> in angular range, power per unit area. The receiver must meet the BER specification while the source is operating at the minimum intensity in angular range into the minimum half-angular range at the maximum link length
- (2) Maximum irradiance E<sub>e</sub> in angular range, power per unit area. The optical delivered to the detector by a source operating at the maximum intensity in angular range at minimum link length must not cause receiver overdrive distortion and possible ralated link errors. If placed at the active output interface reference plane of the transmitter, the receiver must meet its bit error ratio (BER). For more definitions see the document "Symbols and Terminology" on the Vishay website
- (3) Equivalent to IrDA background light and electromagnetic field test: fluorescent lighting immunity
- (4) RXD output is edge triggered by the rising edge of the optical input signal. The output pulse duration is independent of the input pulse duration
- (5) The radiant intensity can be adjusted by the external current limiting resistor to adapt the intensity to the desired value. The given value is for maximum link distance operating the transceiver without current control resistor (R<sub>1</sub> = 0 Ω) and using the internal current control

#### RECOMMENDED CIRCUIT DIAGRAM

Operated with a clean low impedance power supply the TFBS9701 needs no additional external components. However, depending on the entire system design and board layout, additional components may be required (see Fig. 1).

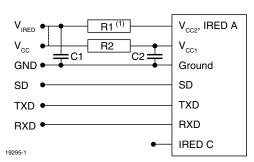


Fig. 1 - Recommended Application Circuit

#### Note

(1) R1 is optional when reduced intensity is used

eliminates the inductance of the power supply line. This one should be a tantalum or other fast capacitor to guarantee the fast rise time of the IRED current. The resistor R1 is the current limiting resistor, which may be used to reduce the operating current to levels below the specified controlled values for saving battery power.

Vishay's transceivers integrate a sensitive receiver and a built-in power driver. The combination of both needs a careful circuit board layout. The use of thin, long, resistive and inductive wiring should be avoided. The shutdown input must be grounded for normal operation, also when the shutdown function is not used.

TABLE 1 - RECOMMENDED APPLICATION CIRCUIT COMPONENTS					
COMPONENT	RECOMMENDED VALUE				
C1	4.7 μF				
C2	0.1 μF, ceramic				
R1	Depends on current to be adjusted				
R2	47 Ω				

The inputs (TXD, SD) and the output RXD should be directly

The capacitor C1 is buffering the supply voltage and



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connected (DC - coupled) to the I/O circuit. The capacitor C2 combined with the resistor R2 is the low pass filter for smoothing the supply voltage. R2, C1 and C2 are optional and dependent on the quality of the supply voltages  $V_{\rm CC}1$  and injected noise. An unstable power supply with dropping voltage during transmission may reduce the sensitivity (and transmission range) of the transceiver.

The placement of these parts is critical. It is strongly recommended to position C2 as close as possible to the transceiver pins.

When extended wiring is used as in bench tests the inductance of the power supply can cause dynamically a voltage drop at  $V_{\rm CC2}$ . Often some power supplies are not able to follow the fast current rise time. In that case another 4.7  $\mu F$  (type, see table under C1) at  $V_{\rm CC2}$  will be helpful.

Under extreme EMI conditions as placing an RF-transmitter antenna on top of the transceiver, we recommend to protect all inputs by a low-pass filter, as a minimum a 12 pF capacitor, especially at the RXD port.

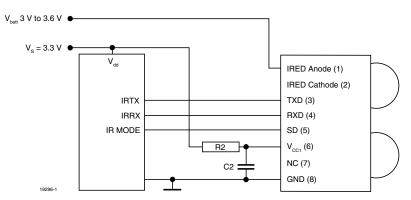


Fig. 2 - Typical Application Circuit

Figure 2 shows an example of a typical application for to work with a separate supply voltage  $V_S$  and using the transceiver with the IRED Anode connected to the unregulated battery  $V_{batt}$ . This method reduces the peak load of the regulated power supply and saves therefore costs. Alternatively all supplies can also be tied to only one voltage source. R1 and C1 are not used in this case and are depending on the circuit design in most cases not necessary.

#### I/O AND SOFTWARE

In the description, already different I/Os are mentioned. Different combinations are tested and the function verified with the special drivers available from the I/O suppliers. In special cases refer to the I/O manual, the Vishay application notes, or contact directly Vishay Sales, Marketing or Application.

For operating at RS232 ports the ENDECS TIR1000 or MCP2122 is recommended.

#### Note

 TFBS9711 echoes the TXD signal at the RXD output during transmission. For communication this signal is to be correctly ignored by the controller or the software. The echo signal is implemented for test purposes in mass production



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TABLI	TABLE 2 - TRUTH TABLE									
		INPUTS	OUTI	PUTS	REMARK					
SD	TXD	OPTICAL INPUT IRRADIANCE mW/m <sup>2</sup>	RXD	TRANSMITTER	OPERATION					
High > 1 ms	х	x	Weakly pulled (500 k $\Omega$ ) to V <sub>CC1</sub>	0	Shutdown					
Low	High	х	Low (active)	l <sub>e</sub>	Transmitting					
Low	High > 100 μs	x	High inactive	0	Protection is active					
Low	Low	< 4	High inactive	0	Ignoring low signals below the IrDA defined threshold for noise immunity					
Low	Low	> min. detection threshold irradiance < max. detection threshold irradiance	Low (active)	0	Response to an IrDA compliant optical input signal					
Low	Low	> min. detection threshold irradiance	Undefined	0	Overload conditions can cause unexpected outputs					

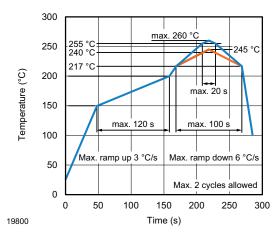
#### **ASSEMBLY INSTRUCTIONS**

#### **Reflow Soldering**

- Reflow soldering must be done within 72 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

#### **Manual Soldering**

- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off



#### **PACKAGE DIMENSIONS** in millimeters

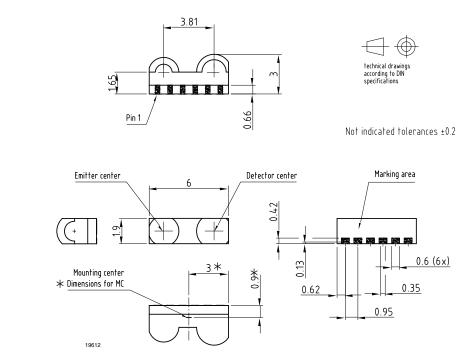


Fig. 3 - Package Drawing of TFBS9711, Tolerance of Height is +0.1 mm, -0.2 mm, other Tolerances ± 0.2 mm

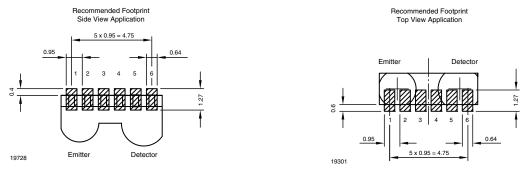
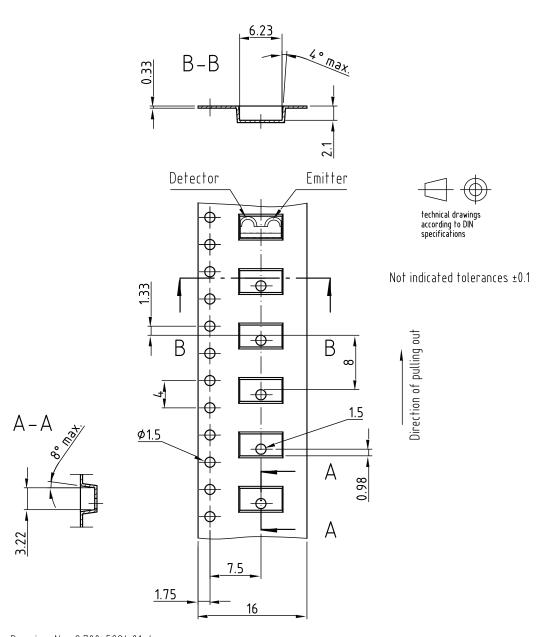


Fig. 4 - Soldering Footprints

#### TAPE DIMENSIONS FOR TR1 AND TR3 in millimeters



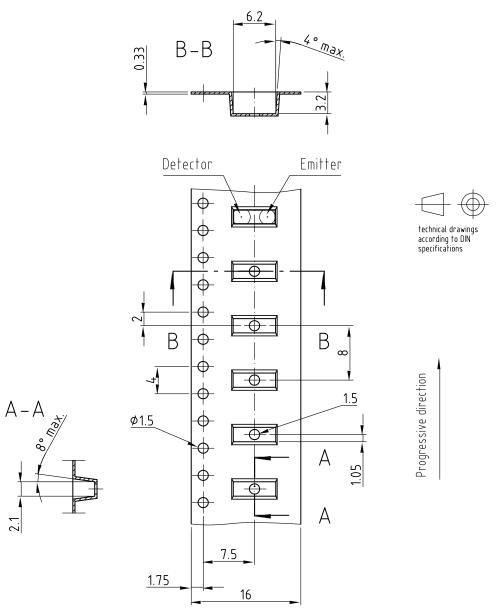
Drawing-No.: 9.700-5294.01-4

Issue: 1; 08.12.04

19613



### **TAPE DIMENSIONS FOR TT1** in millimeters

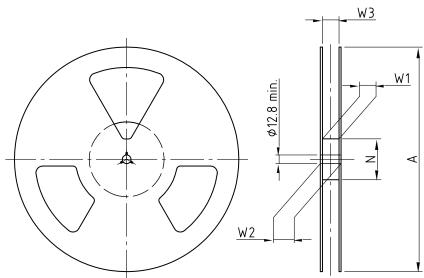


Drawing-No.: 9.700-5295.01-4

Issue: 1; 08.12.04

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#### **REEL DIMENSIONS** in millimeters



Reel hub 2:1

Drawing-No.: 9.800-5090.01-4 Issue: 1; 29.11.05

14017

Form of the leave open of the wheel is supplier specific.

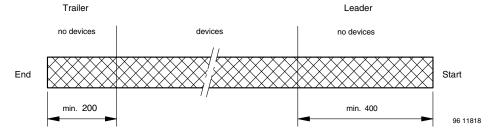
Dimension acc. to IEC EN 60 286-3



technical drawings according to DIN specifications

TAPING VARIANT	TAPE WIDTH (mm)	A MAX. (mm)	N (mm)	W <sub>1</sub> MIN. (mm)	W <sub>2</sub> MAX. (mm)	W <sub>3</sub> MIN. (mm)	W <sub>3</sub> MAX. (mm)
TT1 / TR1	16	180	60	16.4	22.4	15.9	19.4
TT3 / TR3	16	330	50	16.4	22.4	15.9	19.4

#### **LEADER AND TRAILER DIMENSIONS** in millimeters



#### **COVER TAPE PEEL STRENGTH**

According to DIN EN 60286-3 0.1 N to 1.3 N  $300 \pm 10$  mm/min. 165° to 180° peel angle

#### **LABEL**

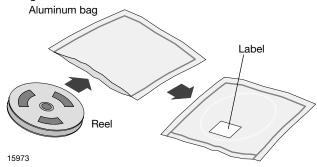
#### Standard bar code labels for finished goods

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.



#### **DRY PACKING**

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



#### FINAL PACKING

The sealed reel is packed into a cardboard box.

#### RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

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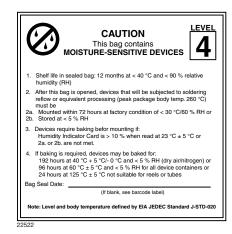
After more than 72 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition: 192 h at  $40 \,^{\circ}\text{C} + 5 \,^{\circ}\text{C}$  / -  $0 \,^{\circ}\text{C}$  and <  $5 \,^{\circ}\text{K}$  RH (dry air / nitrogen)

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or

24 h at 125 °C + 5 °C not suitable for reel or tubes.

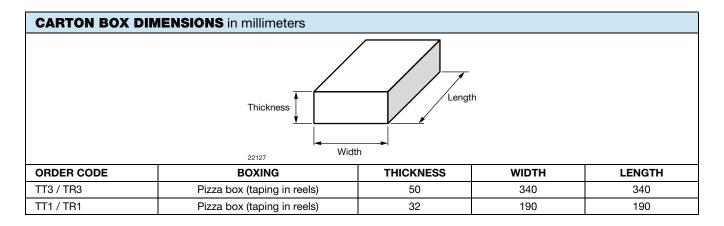
An EIA JEDEC® standard J-STD-020 level 4 label is included on all dry bags.



EIA JEDEC standard J-STD-020 level 4 label is included on all dry bags

#### **OUTER PACKAGING**

The sealed reel is packed into a pizza box.





PLAIN WRITING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	XXXXXX+	Company logo
Long bar code top	Туре	Length
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
Short bar code bottom	Туре	Length
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17

#### **ESD PRECAUTION**

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

# VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.



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### **Legal Disclaimer Notice**

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